

AMENDMENTS TO THE ABSTRACT

Please substitute the following paragraph(s) for the abstract now appearing in the currently filed specification.

A temperature control system for ~~multiple process components in a semiconductor~~ processing facility includes a common cooling unit for controlling the temperature of a cooling fluid and multiple remote temperature control modules ~~in fluid communications with the common cooling unit~~ that separately control the temperatures of the multiple process components. The ~~remote~~ temperature control modules are ~~located~~ near the process components and ~~each remote temperature control module~~ includes a circulation loop for the cooling fluid from the common cooling unit and a circulation loop for a heat transfer fluid that is received from a ~~process~~ component. A heat exchanger within the ~~remote~~ temperature control module allows heat ~~to be transferred from~~ between the heat transfer fluid ~~to~~ and the cooling fluid, thereby ~~providing~~ cooling to the ~~process~~ component. A heat source may also be included within the ~~remote~~ temperature control module to provide heat to the heat transfer fluid and ~~therefore~~ to the ~~process~~ component. The cooling unit may be a refrigeration unit that provides compressed refrigerant to the ~~remote~~ temperature control modules ~~which and the remote temperature control modules~~ may include an upstream thermal expansion valve and a downstream refrigerant flow control valve that form an evaporation chamber for the compressed refrigerant.

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